PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7804841

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
SUPERIOR INDUSTRIES, INC.	02/14/2023

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 12

Property Type	Number	
Application Number:	17646514	
Application Number:	17646840	
Application Number:	17653021	
PCT Number:	US2016046376	
PCT Number:	US2017038623	
PCT Number:	US2017040061	
PCT Number:	US2017043276	
PCT Number:	US2018058302	
PCT Number:	US2019048614	
PCT Number:	US2019058975	
PCT Number:	US2020045529	
PCT Number:	US2021072251	

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PATENT

REEL: 062740 FRAME: 0750

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ATTORNEY DOCKET NUMBER:	M34255-00064
NAME OF SUBMITTER:	LINDSAY R. BUSER
SIGNATURE:	/LINDSAY R. BUSER/
DATE SIGNED:	02/20/2023

Total Attachments: 4

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PATENT REEL: 062740 FRAME: 0751

NOTICE OF GRANT OF SECURITY INTEREST IN PATENTS

Dated: February 14, 2023

United States Patent and Trademark Office

Ladies and Gentlemen:

Please be advised that pursuant to that certain Amended and Restated Pledge and Security Agreement dated as of May 17, 2021 (as amended, modified, extended or restated from time to time, the "Security Agreement") by and among SUPERIOR INDUSTRIES, INC., a Minnesota corporation ("Grantor"), the other loan parties from time to time party thereto and JPMORGAN CHASE BANK, N.A., in its capacity as administrative agent ("Administrative Agent"), Grantor has granted to Administrative Agent, on behalf of and for the ratable benefit of the Secured Parties (as defined in the Security Agreement), a continuing security interest in and continuing lien upon, among other things, the patent applications set forth on Exhibit A attached hereto.

Grantor and Administrative Agent hereby acknowledge and agree that the security interest in the foregoing patent applications (a) may only be terminated in accordance with the terms of the Security Agreement and (b) is not to be construed as an assignment of any patent applications.

[Remainder of page intentionally blank; signature page follows]

PATENT REEL: 062740 FRAME: 0752 Very truly yours,

SUPERIOR INDUSTRIES, INC., a Minnesota corporation

Name:

Title OCA

[Signature page to Notice of Grant of Security Interest in Patents]

Acknowledged and accepted:

JPMORGAN CHASE BANK, N.A. as Administrative Agent

Name: Martin Cherney Title: Authorized Officer

[Signature page to Notice of Grant of Security Interest in Patents]

PATENT REEL: 062740 FRAME: 0754

EXHIBIT A

PATENT APPLICATIONS

Patent Application Number	Filing Date
17/646,514	12/30/2021
17/646,840	1/3/2022
17/653,021	3/1/2022
PCT/US16/46376	8/10/2016
PCT/US17/38623	6/21/2017
PCT/US17/40061	6/29/2017
PCT/US17/43276	7/21/2017
PCT/US18/58302	10/30/2018
PCT/US19/48614	8/28/2019
PCT/US19/58975	10/30/2019
PCT/US20/45529	8/7/2020
PCT/US21/72251	11/4/2021
	17/646,514 17/646,840 17/653,021 PCT/US16/46376 PCT/US17/38623 PCT/US17/40061 PCT/US17/43276 PCT/US18/58302 PCT/US19/48614 PCT/US19/58975

PATENT REEL: 062740 FRAME: 0755

RECORDED: 02/20/2023